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# U1897 **N-Channel JFET Switch**

## **Features**

- · This device is designed for low level analog switching, sample and hold circuits and chopper stabalized amplifiers.
- · Sourced from Process 51.
- · See J111 for characteristics.



## Absolute Maximum Ratings \* $\ensuremath{\text{T}_{a}\text{=}25^{\circ}\text{C}}$ unless otherwise noted

Symbol	Parameter	Value	Units	
$V_{DG}$	Drain-Gate Voltage 40		V	
$V_{GS}$	Gate-Source Voltage	-40	٧	
I <sub>GF</sub>	Forward Gate Current 50		mA	
$T_J$ , $T_{STG}$	T <sub>J</sub> , T <sub>STG</sub> Operating and Storage Junction Temperature Range		°C	

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

## Thermal Characteristics $^{\star}$ $T_a$ =25°C unless otherwise noted

Symbol	Parameter	Value	Units	
$P_{D}$	Total Device Dissipation Derate above 25°C	625 5.0	mW mW/°C	
$R_{ heta JC}$	Thermal Resistance, Junction to Case	125	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W	

1

NOTES:

1) These ratings are based on a maximum junction temperature of 150°C.

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

<sup>\*</sup> Device mounted on FR-4 PCB 1.6" × 1.6" × 0.06"

# **Electrical Characteristics \*** $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Conditions	Min.	Max	Units		
Off Charact	Off Characteristics						
V <sub>(BR)GS</sub>	Gate-Source Breakdown Voltage	$I_G = -1.0 \mu A, V_{DS} = 0$	-40		V		
V <sub>GS(off)</sub>	Gate-Source Cutoff Voltage	$V_{DS} = 20 \text{ V}, I_{D} = 1.0 \text{ nA}$	-5.0	-10	V		
I <sub>DGO</sub>	Drain-Gate Leakage Current	V <sub>DG</sub> = 20 V, I <sub>S</sub> = 0		-200	рА		
On Charact	eristics						
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current *	$V_{DS} = 20 \text{ V}, V_{GS} = 0$	30		mA		
r <sub>DS(on)</sub>	Static Drain-Source On Resistance	$I_D = 1.0 \text{ mA}, V_{GS} = 0$		30	Ω		
Small Signa	al Characteristics						
r <sub>ds(on)</sub>	Drain-Source On Resistance	$V_{DS} = V_{GS} = 0$ , f= 1.0 kHz		30	Ω		
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 20, V_{GS} = 0, f = 1.0 \text{ MHz}$		16	pF		
C <sub>rss</sub>	Reverse Transfer Capacitance	V <sub>GS</sub> = -20 V, f = 1.0 MHz		3.5	pF		
Switching (	Characteristics						
t <sub>on</sub>	Turn-On Time	$I_{D(on)} = 6.6 \text{ mA}$		25	ns		
t <sub>off</sub>	Turn-Off Time	V <sub>GS(off)</sub> = 12.0 V		40	ns		

<sup>\*</sup> Pulse Test: Pulse Width  $\leq 300 \mu s,$  Duty Cycle  $\leq 2.0\%$ 

- 1. These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

  2. These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

  3. These ratings are based on a maximum junction temperature of 150degrees C.





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